

Features

- Split Gate Trench MOSFET Technology
- Low $R_{DS(on)}$ & FOM
- Extremely Low Switching Loss
- Excellent Stability and Uniformity
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)
- Moisture Sensitivity Level 1

Maximum Ratings

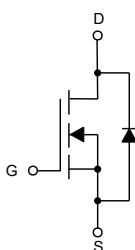
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 70°C/W Junction to Ambient⁽¹⁾
- Thermal Resistance: 0.8°C/W Junction to Case

Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	V_{DS}	40	V	
Gate-Source Voltage	V_{GS}	±20	V	
Continuous Drain Current ⁽²⁾	I_D	$T_C=25^\circ C$	160	A
		$T_C=100^\circ C$	100	A
Pulsed Drain Current ⁽³⁾	I_{DM}	480	A	
Avalanche Energy ⁽⁴⁾	E_{AS}	720	mJ	
Total Power Dissipation ⁽⁵⁾	P_D	150	W	

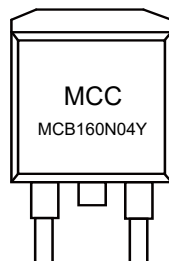
Note:

1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ $t \leq 10s$ and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. $T_J = 25^\circ C$, $V_{DD} = 25V$, $L = 3mH$, $I_{AS} = 22A$

Internal Structure and Marking Code

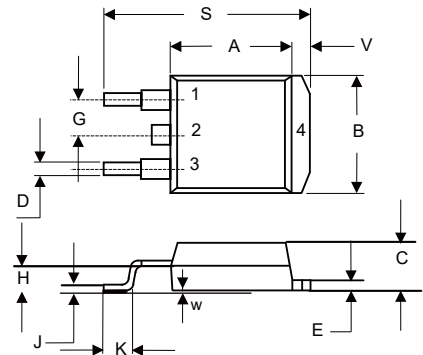


1. Gate
- 2,4. Drain
3. Source



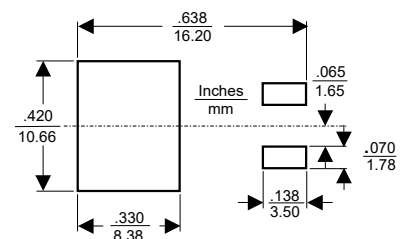
N-CHANNEL MOSFET

D2-PAK



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.331	0.370	8.40	9.40	
B	0.378	0.417	9.60	10.60	
C	0.165	0.189	4.20	4.80	
D	0.027	0.037	0.68	0.94	
E	0.045	0.055	1.14	1.40	
G	0.010		2.54		TYP.
H	0.096	0.134	2.43	3.40	
J	0.011	0.025	0.28	0.64	
K	0.071	0.131	1.80	3.32	
S	0.575	0.625	14.60	15.87	
V	0.042	0.058	1.07	1.47	
W	0.000	0.010	0.00	0.25	

Suggested Solder Pad Layout



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	40			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=40V, V_{GS}=0V$			1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.8	2.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$		1.5	1.85	m Ω
		$V_{GS}=4.5V, I_D=20A$		2.3	2.8	
Diode Characteristics						
Continuous Body Diode Current	I_S				160	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=20A$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F=20A, dI_F/dt=100A/\mu s$		56		ns
Reverse Recovery Charge	Q_{rr}			54		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$		7100		pF
Output Capacitance	C_{oss}			1298		
Reverse Transfer Capacitance	C_{riss}			55		
Total Gate Charge	Q_g	$V_{DS}=20V, I_D=20A$		132		nC
Gate-Source Charge	Q_{gs}			25		
Gate-Drain Charge	Q_{gd}			24.6		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=20V, V_{GS}=10V, R_G=2.2\Omega, I_{DS}=20A$		18.8		ns
Turn-On Rise Time	t_r			70		
Turn-Off Delay Time	$t_{d(off)}$			136.8		
Turn-Off Fall Time	t_f			92.3		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

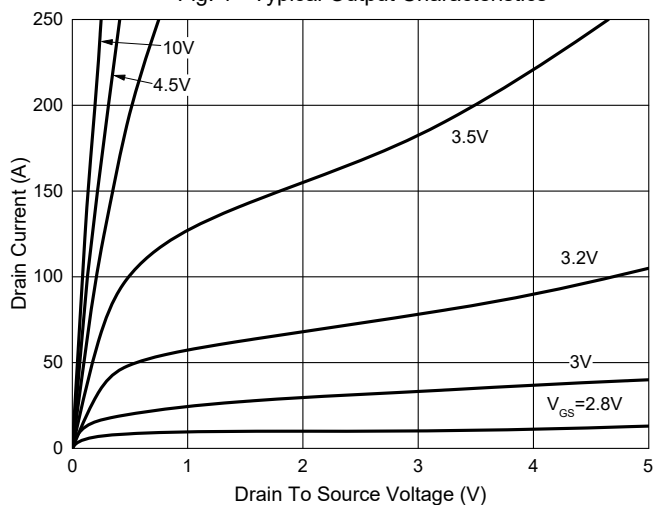


Fig. 2 - Transfer Characteristics

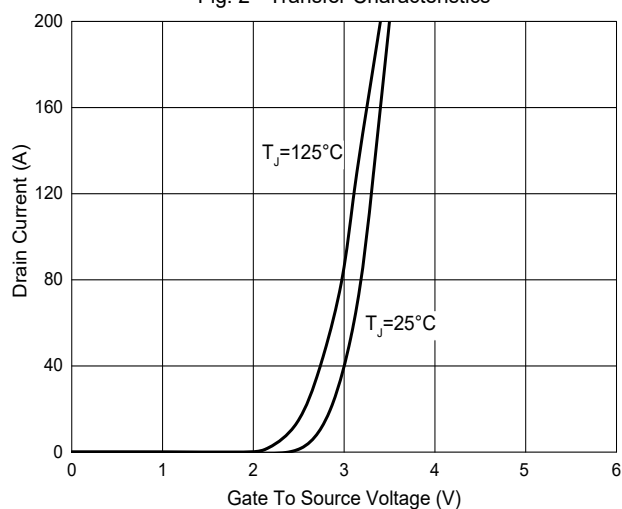


Fig. 3 - R_{DS(ON)} - V_{GS}

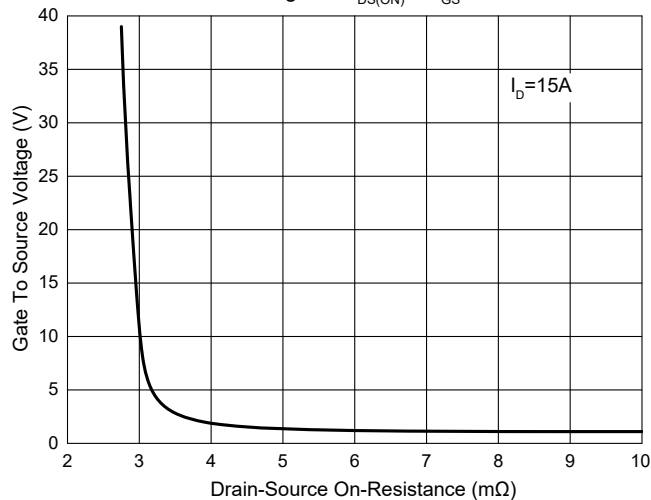


Fig. 4 - Drain-Source on Resistance

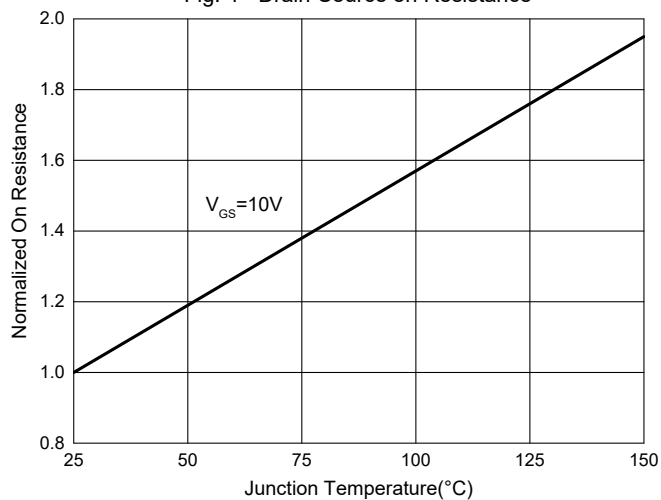


Fig. 5 - Capacitance Characteristics

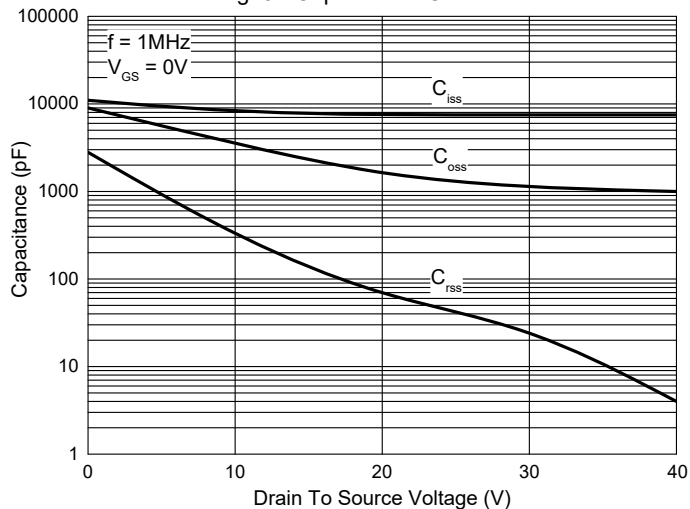
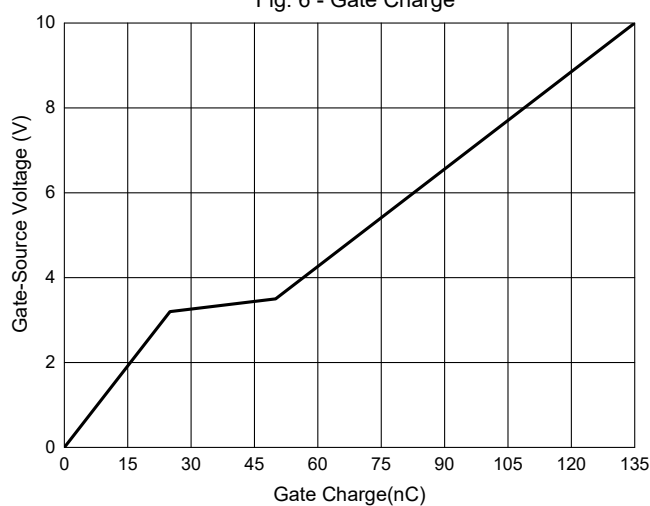


Fig. 6 - Gate Charge



Curve Characteristics

Fig. 7 - Safe Operation Area

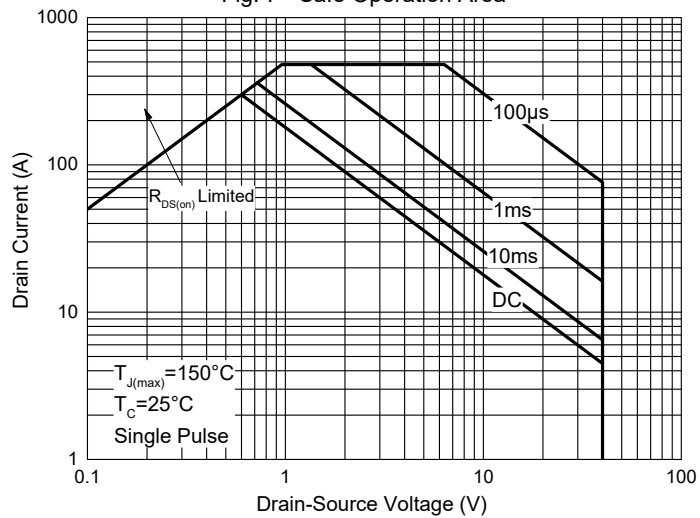
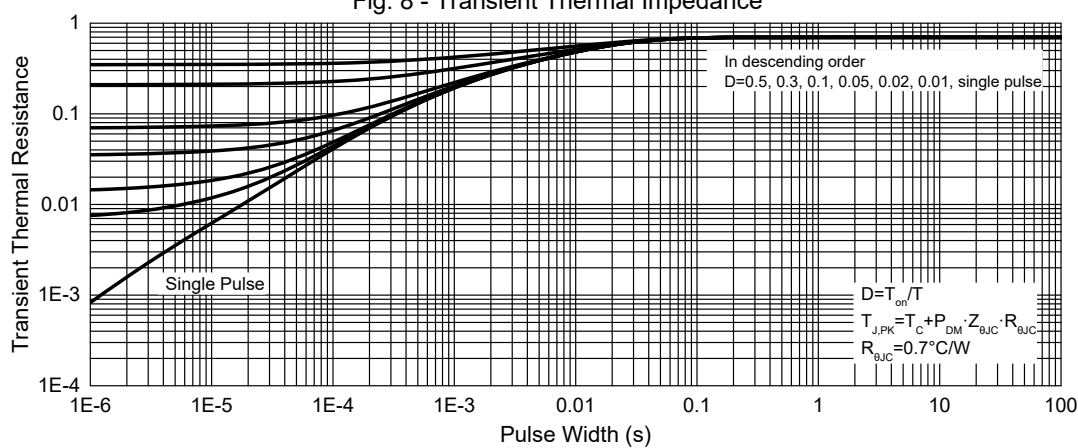


Fig. 8 - Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 800pcs/Reel
Part Number-BP	Tube: 5Kpcs/Ctn

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